



PRODUCT NUMBER DESCRIPTION :
59132 - X XX - XX - XXX XLF

PLATING

- S = 0.38µm GOLD ON CONTACT AREA
0.38µm GOLD ON TAIL
G = 0.76µm GOLD ON CONTACT AREA
0.76µm GOLD ON TAIL
F = 0.20µm GOLD ON CONTACT AREA
0.20µm GOLD ON TAIL
T = 0.76µm GOLD ON CONTACT AREA
2.54µm 100% MATTE TIN ON TAIL
H = GOLD FLASH ON CONTACT AREA
2.54µm 100% MATTE TIN ON TAIL

LEAD FREE (SEE NOTE 11)

RETENTION (SEE NOTES 6 & 10)
R: RETENTIVE LEG

STACKER HEIGHT (SEE NOTE 7)

PACKAGING: - = BAGS
(SEE NOTE 5) U = TUBES

POSITIONS PER ROW = "N"
(02 TO 25)

OMIT FROM PRODUCT NUMBER FOR
LEAD FREE WITH RETENTIVE LEG PRODUCT

NOTES:

1. MATERIAL HOUSING: HIGH TEMPERATURE THERMOPLASTIC
UL 94V-0, COLOR BLACK
2. MATERIAL TERMINAL: COPPER ALLOY

- ③ TO DETERMINE DIMENSIONS:
N=NUMBER OF POSITIONS PER ROW
EX.: 10 POS., N x 2.00 = 20.00 TOTAL POSITIONS

4. 0.9kg MIN. PIN RETENTION IN EITHER DIRECTION.

5. PACKAGING;
(A) STANDARD PACKAGING: IN POLY BAGS.
(B) SPECIAL PACKAGING: IN TUBE.
FOR ALL SPECIAL PACKAGING,FCI MUST BE
CONTACTED FOR AVAILABILITY IN SIZE REQUESTED.

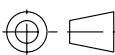
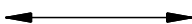
- ⑥ RETENTION LEG:
2.3kg MAX INSERTION FORCE AND 1 kg MIN RETENTION
FORCE PER RETENTIVE PIN USING 1.57 THICK CIRCUIT
BOARD AND RECOMMENDED HOLE PATTERN. RETENTIVE
LOCATION AT THE DISCRETION OF THE MANUFACTURER.
RETENTION IS TWO PINS PER PART ADJACENT TO ONE
ANOTHER.

- ⑦ STACK HEIGHT IS DETERMINED BY CUSTOMER APPLICATION
REQUIREMENTS. SPECIFIED IN mm.
EXAMPLE: 3.7mm STACK HEIGHT=59132-XXX-XX-037X.

- ⑧ POST LENGTH IS DETERMINED BY: (OAL)-(3.00)-(STACK HGT.)
=POST LENGTH.MINIMUM MATING LENGTH TO BE 2.0mm.

PIN STYLE	OAL
22	08.2
24	09.6
26	10.2
28	11.8
30	13.5
32	14.1
34	15.6
36	17.1
38	19.1
40	21.1
42	18.0

- ⑨ DIM 1.0 APPLIES TO MOLDED SIDE(S) ONLY. IF SIDE(S) ARE
BROKEN, DIM 1.5 MAX APPLIES.
- ⑩. OMIT FROM PRODUCT NUMBER IF FEATURE IS NOT APPLICABLE.
- ⑪. P/N:59132-XXXLF IS SAME AS P/N:59132-XXX. THE SUFFIX 'LF'
IS ADDED FOR EASY LEAD FREE IDENTIFICATION.
12. THE HOUSING WILL WITHSTAND EXPOSURE TO 255°C PEAK
TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED
OR VAPOR PHASE REFLOW OVEN.
13. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK
TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER
APPLICATION WITH A 1.57MM MINIMUM THICK CIRCUIT BOARD.
14. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND
OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
15. A  SYMBOL WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE
WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION.

dr	wcadmin	2010/10/31			size	A3	scale	5:1
eng	Guo-Min Sun	2014/10/29			ecn no	ELX-N-19241-1		
chr	-	-						
appr	Feagle Pan	2014/10/29	product family		MINITEK		rel level	Released
	title	2.0MM UNSHROUDED HEADER BOARD TO BOARD THRU-HOLE			dwg no	59132		rev
www.fci.com	cat. no.	-	Product - Customer Drw				sheet 2 of 2	

